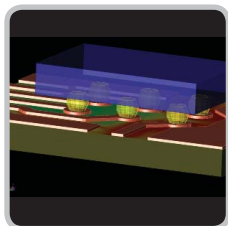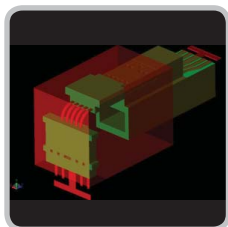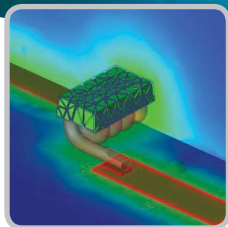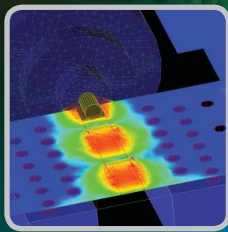# Agilent EEsof EDA
EMPro

3D Electromagnetic Modeling and Simulation
Environment Integrated with your
ADS Design Flow
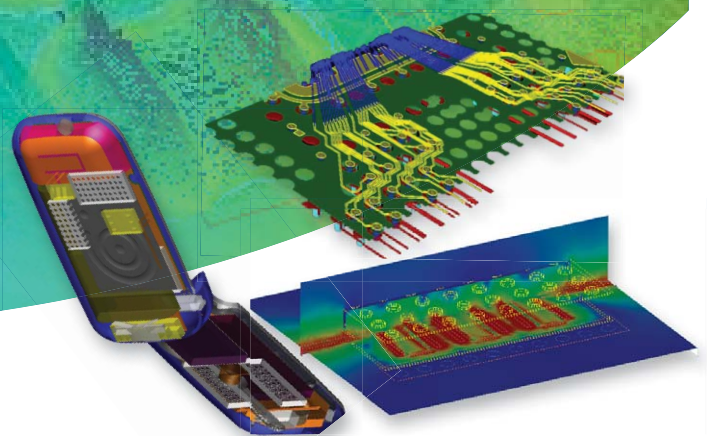
Electromagnetic Professional (EMPro) is a 3D modeling and simulation environment for analyzing the 3D electromagnetic (EM) effects of high-speed and RF/microwave components. EMPro features a modern design, simulation and analysis environment, high capacity time- and frequency-domain simulation technologies and integration with ADS, the industry's leading RF/microwave and high-speed design environment.

Agilent Technologies

Agilent EM Solution Overview

EMPro delivers the following key capabilities:

Modern, efficient 3D solid modeling environment

EMPro provides the flexibility of drawing arbitrary 3D structures and the convenience of importing existing CAD files. You can create 3D shapes, add material properties, set up simulations, and view results—all within the EMPro environment.

Time- and frequency-domain simulation technology

3D structures can be analyzed in EMPro using the same FEM simulator available in ADS. FEM is a frequency-domain technology widely used for RF/microwave applications. For electrically large problems, such as antennas and some signal integrity analyses, the finite difference time domain (FDTD) simulator can be used.
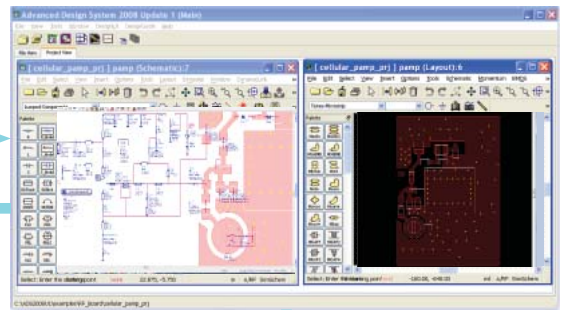
Integration with ADS

Parameterized 3D components can be created in EMPro and placed in a layout design in ADS. The 3D FEM simulator in ADS can then be used to simulate the combination of the 2D layout and the 3D EM component.
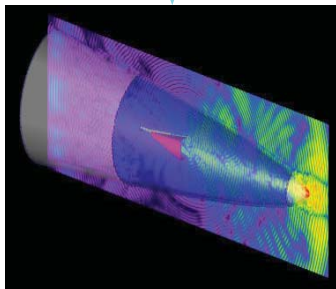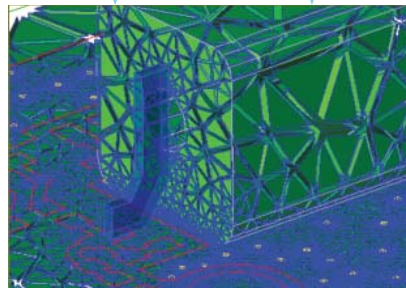
EMPro Environment
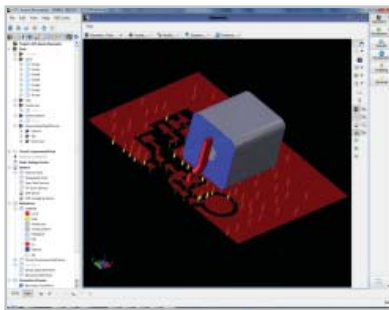
ADS Platform

Parameterized
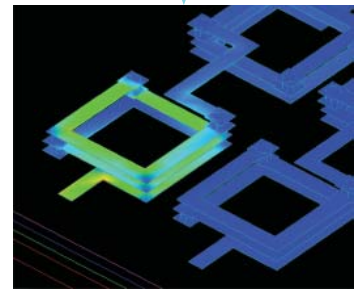EM components
from EMPro

Layout objects
from ADS

FDTD simulator
Finite difference time domain

FEM simulator
Finite element method

Momentum simulator
Method of moments

Figure 1. Agilent provides multiple EM simulation technologies integrated with the ADS design flow.

EMPro Simulation Capabilities

There are several different technical approaches to EM simulation, each with their own advantages in certain application areas. The most established 3D EM simulation technologies are FEM and FDTD. Both of these technologies are available in EMPro.

Finite element method

FEM is a frequency-domain technique that can handle arbitrary shaped structures such as bondwires, conical shape vias and solder balls/bumps where z-dimensional changes appear in the structure. FEM solvers can also simulate dielectric bricks or finite-size substrates.
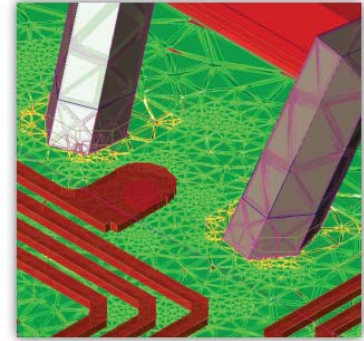
FEM is based on volumetric meshing where the full problem space is divided into thousands of smaller regions and represents the field in each sub-region (element) with a local function. The geometric model is automatically divided into a large number of tetrahedra, where a single tetrahedron is formed by four equilateral triangles. This collection of tetrahedra is referred to as the finite element mesh. The Agilent FEM simulator includes both direct and iterative solvers, and both linear and quadratic basis functions, to solve a broad range of problems. The same FEM simulator is available in both EMPro and ADS.
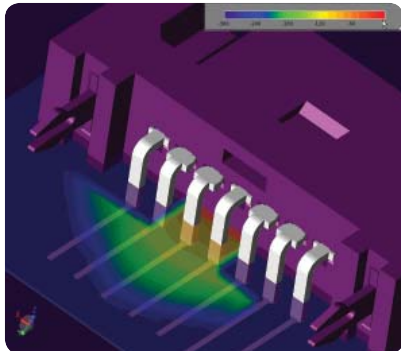
Finite difference time domain

As with FEM, the FDTD method is based on volumetric sampling of the electric and magnetic fields throughout the complete space. Whereas FEM meshes consist of tetrahedral cells, FDTD meshes are typically built from rectangular (Yee) cells. The FDTD method updates the field values while stepping through time, following the electromagnetic waves as they propagate through the structure. As a result, a single FDTD simulation can provide data over an ultra-wide frequency range.

Because of its simple, robust nature and its ability to incorporate a broad range of linear and nonlinear materials and devices, FDTD is used to study a wide range of applications, including: antenna design, microwave circuits, bio/EM effects, EMC/EMI problems, and photonics. FDTD is an inherently parallel method and therefore lends itself very well to the processing capabilities of the most recent advances in CPU (general-purpose processors) and GPU (graphics processors) hardware.

Table 1. Summary comparison of FEM versus FDTD

| FEM	FDTD
Frequency domain method	Time domain method
Tetrahedral mesh cells	Rectangular mesh cells
Good for high-Q structures	Good for broadband applications, physical transitions
Fast for multi-port simulations	Each port requires additional simulation
Based on solving matrix equations; best for electrically small problems	Based on iterative time stepping; less memory intensive for electrically large problems
Multi-threaded; problems can be divided and run in parallel on multi-core CPUs	Highly multi-threaded; problems can be divided and run in parallel on multi-core CPUs and on large GPU cards

Typical EMPro Applications

IC packages
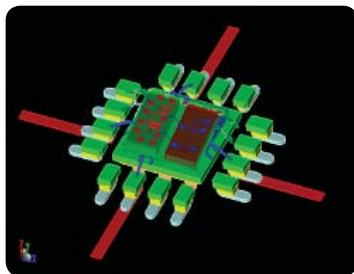
The performance of an RFIC, monolithic microwave integrated circuits (MMIC), high-speed IC, or system-in-package (SIP) is directly impacted by the effects of packaging, including wire bonds and solder balls/bumps. Traditionally, designers had to draw and analyze packages in a separate, 3D EM tool and then laboriously import the results back to the IC or SIP circuit-design environment for a combined analysis. With EMPro, you can efficiently create 3D package structures that can be combined with 2D circuit layouts in ADS. This allows co-design of the IC, package, laminate, and module with circuit simulation and 3D EM simulation in a streamlined design flow.

Multi-layer RF modules
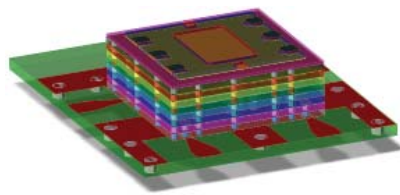
RF modules typically are constructed from multi-layer ceramic or laminate dielectric material with embedded RF passive components between the layers. Such dielectric brick structures cannot be accurately solved by planar EM simulators, which assume infinite dielectric layers and do not account for edge proximity fringing. The embedded RF components are drawn by RF circuit layout macros which would be very time consuming to reproduce in a standalone 3D EM tool. Full 3D EM simulation integrated within the circuit design flow is the ideal solution for these applications.

RF components

RF board designs include 3D components and connectors that need to be characterized to high frequencies. Components such as resonators are sensitive to interactions with the surrounding PC board traces and vias. Such 3D components can be created and simulated in EMPro and then combined with a board layout in ADS for complete 3D EM simulation.
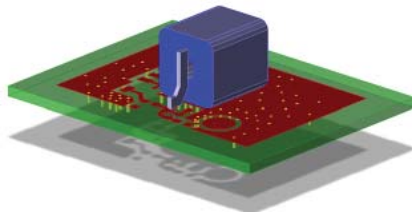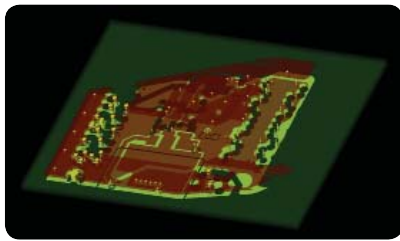
Aerospace/Defense

FDTD simulation has extremely high capacity and can handle large problems found in aerospace/defense applications. For example, FDTD can be used to optimize antenna placement in aircraft and perform Radar Cross Section analysis.
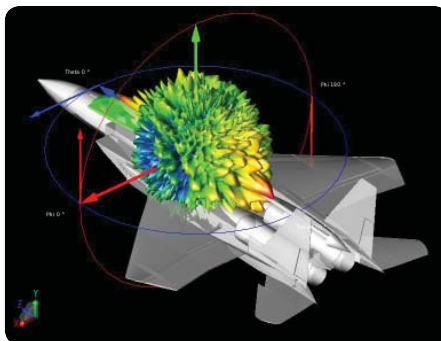
Typical EMPro Applications

PCB Design

With data rates increasing, PCB traces must now be analyzed as RF transmission lines. 3D EM technologies complement 3D planar simulators such as Agilent Momentum for high speed signal integrity analysis, EMI/EMC, and PCB interfaces to connectors and packages.

High-speed connectors

High-speed connector types such as SATA and HDMI now support Gbits/s data throughput. High frequency S-parameter models of connectors can be generated in EMPro and cross-verified with both the FEM and FDTD simulators to give designers twice the confidence in 3D EM simulation accuracy. The models can then be included in an ADS design kit that can be distributed and installed into ADS as a connector library for use in signal-integrity analysis and design of high-speed serial channels.
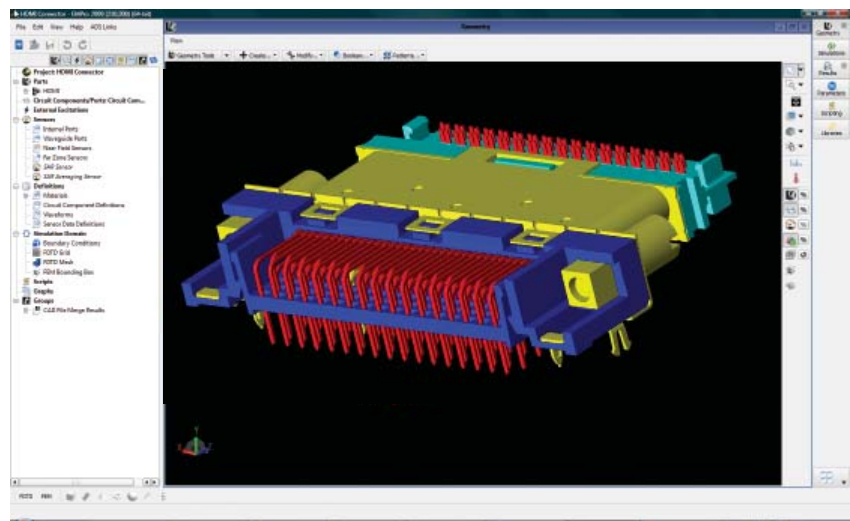
Handset antennas

A critical design task in the development of cellular and networking products is maximizing antenna performance while minimizing antenna size. EMPro can simulate the antenna in realistic surroundings, including the phone components, housing and even the human hand and head. Compliance testing can also be performed, such as specific absorption ratio (SAR) and hearing aid compatibility (HAC).
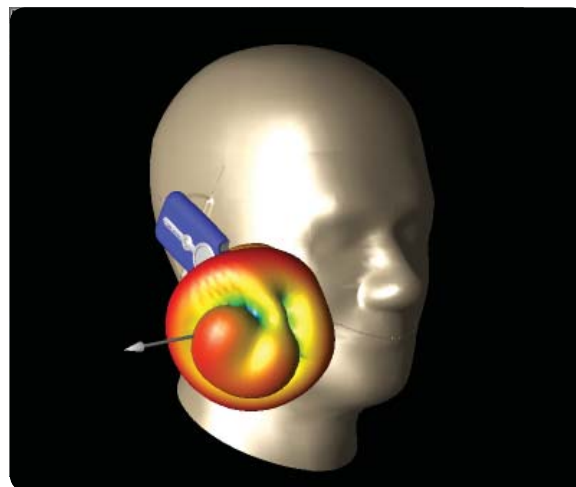
EMPro Environment Overview

Geometry modeling

- Arbitrary 3D structures can be created using the powerful EMPro drawing environment.
- Alternatively, structures can be imported from other CAD environments. Supported file formats include: ACIS, IGES, DXF, STEP, ProE, SolidWorks, ODB++ and others.
- Material properties are assigned to imported or drawn 3D objects using a simple drag-and-drop from an extensive material database onto the 3D objects. Once assigned, the material properties are memorized for subsequent CAD imports, enabling even faster simulation setup.

Draw from spec

Define materials

OR
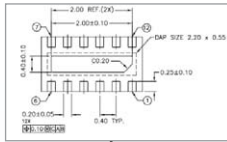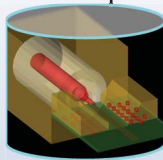
Import CAD file
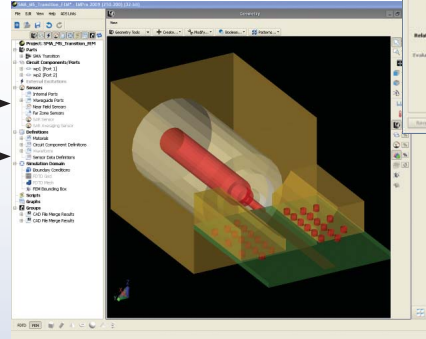
Port/sensor setup

- General voltage and current sources can be placed on the object and the source impedance defined.
- Additionally, for FDTD simulations, external plane wave and Gaussian beam sources can be set up. Sensors are also set up to detect near-field and far-field voltages, currents and field quantities. Special SAR and HAC sensors can be added for compliance testing.
- For FEM simulations, waveguide ports can be set up.

Define internal ports (FDTD, FEM)
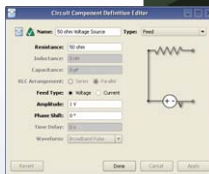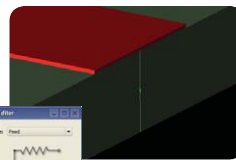
OR

Define waveguide ports (FEM)
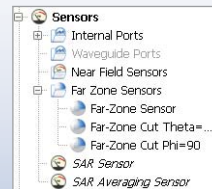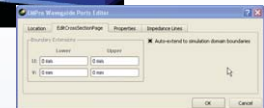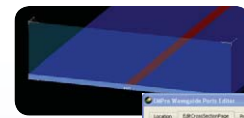
Define sensors

Mesh setup

- For FDTD simulations, a rectangular mesh is generated based on the shapes of the objects. Initial mesh is automatically generated to optimize accuracy and simulation time. Fixed point meshing automatically aligns the mesh with object boundaries. Users can tune the mesh to make further trade-offs between accuracy and speed.
- In a similar fashion, a tetrahedral mesh is generated for FEM simulations. The mesh is optimized for speed/accuracy through a process of automatic adaptive refinement.

Setup FDTD grid/mesh
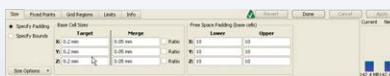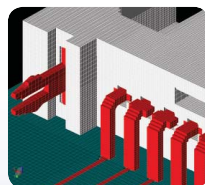
OR

Setup FEM mesh
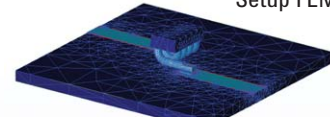
EMPro Environment Overview

Simulation setup

- Either FEM or FDTD simulation can be selected.
- For FEM, a frequency plan is created. Direct and iterative solvers are available and multi-threading capability on a multi-core CPU can be selected.
- For FDTD, multi-threading capability on a multi-core CPU or GPU card(s) can be selected.

Setup simulation

FDTD

FEM
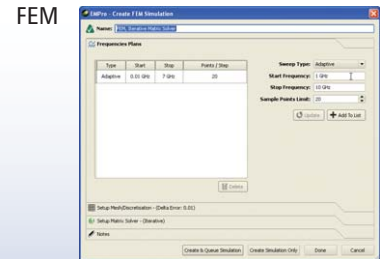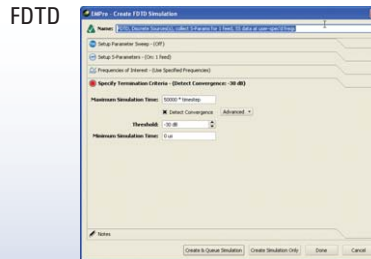
## Results post-processing and viewing

- S-parameter data can be plotted and compared with data from other projects.
- Advanced visualization of fields is available, including cut-plane views.
- Connectivity View can be used to find design errors, where small gaps between conductors might not be visible otherwise.
- Python scripting can be used for advanced post processing, and for automating simulations.

View results
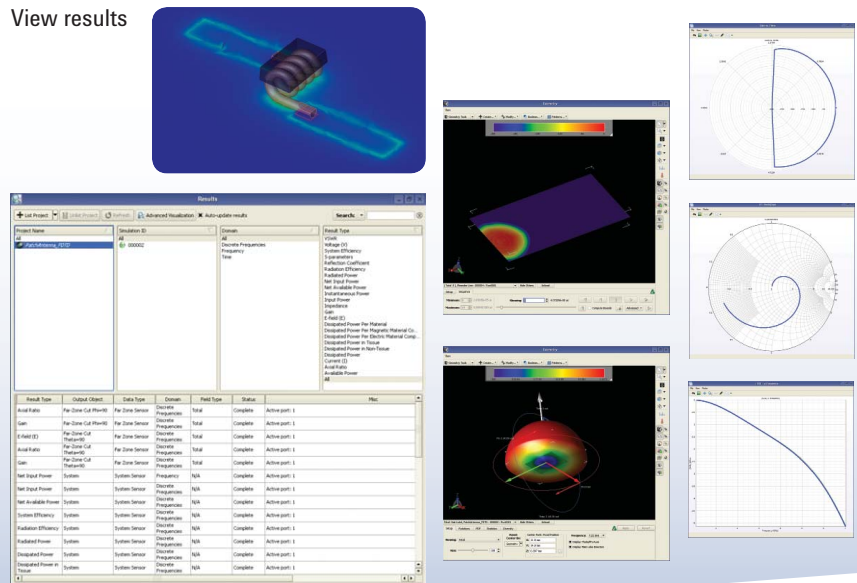
Export 3D EM component to ADS

- 3D structures such as packages, shields, connectors, and surface-mount components can be exported from EMPro to ADS, so that these structures can be simulated together with a 2D circuit layout.
- Components can be parameterized in EMPro to enable sweeps and optimization in ADS.
- The same FEM simulator is used in both EMPro and ADS to simulate the stand-alone component and the combination of the component and ADS layout.

Export to ADS
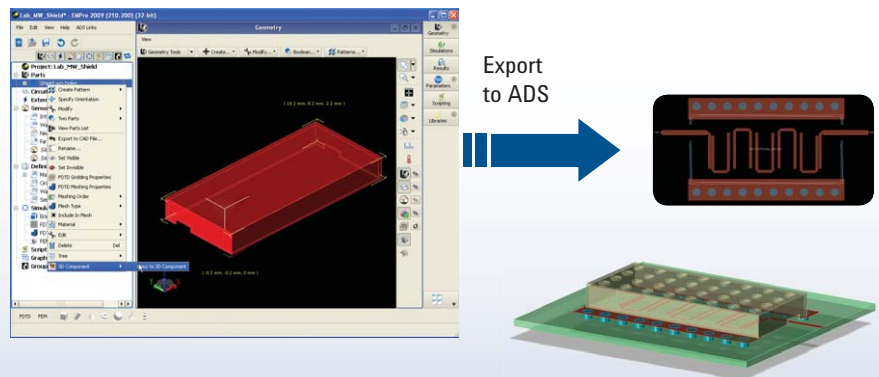
EMPro Product Configuration

EMPro can be purchased as individual UI and simulator elements, or pre-configured bundles.

EMPro bundles are comprised of:

- W2401 EMPro core environment, which enables you to create and import arbitrary 3D structures, and

- Simulator elements, each of which provides specific capabilities.

EMPro bundles			
EMPro elements	W2402B	W2403B	W2404B
W2401 EMPro core element	√	√	√
W2342 Agilent FEM simulator element	√	-	√
W2405 Agilent FDTD simulator element	-	√	√

http://www.agilent.com/find/eesof-fem

http://www.agilent.com/find/eesof-empro

http://www.agilent.com/find/eesof-empro-evaluation

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